

Product Change Notification - IIRA-15OECT725

Date: 28 Apr 2014

Product Category: Memory

Notification subject: CCB 1397.05 Initial Notice: Qualification of HR-5104 die attach film for 24AA1025, 24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026 device families in 8L SOIC package at NSEB (UTL) assembly site.

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

PCN_IIRA-15OECT725_Affected_CPN.xls

PCN_IIRA-15OECT725_Affected_CPN.pdf

Description of Change:

Qualification of HR-5104 die attach film for 24AA1025, 24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026 device families in the 8L SOIC package at NSEB (UTL) assembly site.

Pre Change:

HS-231W die attach film

Post Change:

HR-5104 die attach film

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 15, 2014 (date code: 1429)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

April 28, 2014: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_IIRA-15OECT725_Affected CPN.pdf](#) [PCN_IIRA-15OECT725_Qual Plan.pdf](#) [PCN_IIRA-15OECT725_Affected CPN.xls](#)

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PCN_IIRA-15OECT725
CATALOG_PART_NBR
24AA1025-I/SN
24AA1025T-I/SN
24AA1025T-I/SNVAO
24AA1026-I/SN
24AA1026T-I/SN
24FC1025-I/SN
24FC1025T-I/SN
24FC1026-I/SN
24FC1026T-I/SN
24LC1025-E/SN
24LC1025-E/SN16KV01
24LC1025-I/SN
24LC1025T-E/SN
24LC1025T-E/SN16KVAO
24LC1025T-I/SN
24LC1026-E/SN
24LC1026-I/SN
24LC1026T-E/SN
24LC1026T-I/SN



MICROCHIP

QUALIFICATION PLAN

PCN #: IIRA-15OECT725

**Date:
April 9, 2014**

**Qualification of HR-5104 die attach film for 24AA1025,
24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026
device families in the 8L SOIC package at NSEB (UTL)
assembly site.**

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Purpose: _____ Qualification of HR-5104 die attach film for 24AA1025, 24AA1026, 24FC1025, 24FC1026, 24LC1025 and 24LC1026 device families in the 8L SOIC package at NSEB (UTL) assembly site.

MP code: _____ 360107C2XB00
Part No.: _____ 24AA1025
Fab/Node: _____ 160K
Die size D5AB2 _____ 81.2x113.5- top and bottom
_____ 47x89 - spacer
BD No.: _____ BDE-002615-01
CCB No.: _____ 1397.05

Package code: _____ C2
Type: _____ 8L SOIC
Width or Size: _____ 150mils
Die thickness: _____ 7mils top/ 7 mil bottom / 7 mils spacer
MSL: _____ MSL1

Lead frame:
Paddle size: _____ 95x130mils
Manufacturer: _____ ASM
Material: _____ C194
Surface: _____ no treatment
Paddle plating: _____ Ag spot
Process: _____ stamped
Lead Lock: _____ Yes
Part Number: _____ FD0258
Strip dimensions: _____ 238x70mm

Wire:
Material: _____ Au

Die Attach Film:
Part Number: _____ HR-5104
Manufacturer: _____ Hitachi
Conductive: _____ No

Mold Compound:
Part Number: _____ G600
Manufacturer: _____ Sumitomo

Lead finish: _____ Matte tin

Reliability Test plan: _____ STD Package Reliability Test plan on each package.
Per QC139000

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	3	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	3	3	24	0	5	30 bonds from a minimum of 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175°C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C and 85°C. 1lot to be tested at 125°C	45	5	3	150	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. Perform SAM analysis using the standard sample size. MSL1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and 85°C. 1lot to be tested at 125°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at +25°C and 85°C. 1lot to be tested at 125°C 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.